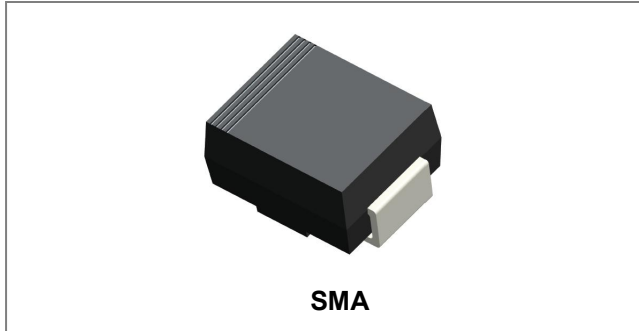


## SS22A THRU SS220A SCHOTTKY RECTIFIER



### Features

- Schottky Brier Chip
- Low Power Loss, High Efficiency
- Ideally Suited for Automatic Assembly
- Surge Overload Rating to 50A Peak
- Plastic Case Material has UL Flammability Classification Rating 94V-0
- This is a Pb – Free Device
- All SMC parts are traceable to the wafer lot
- Additional testing can be offered upon request

### Circuit Diagram



### Mechanical Data

- Case: SMA, Molded plastic
- Terminals: Plated leads solderable per MIL-STD-750, Method 2026 guaranteed
- Polarity: Color band denotes cathode end
- Mounting Position: Any

### Maximum Ratings and Electrical Characteristics @T<sub>A</sub>=25°C unless otherwise specified

Type Number	Symbol	SS 22A	SS 23A	SS 24A	SS 245A	SS 25A	SS 26A	SS 28A	SS 210A	SS 215A	SS 220A	Units
Peak Repetitive Reverse Voltage Working Peak Reverse Voltage DC Blocking Voltage	V <sub>RRM</sub> V <sub>RWM</sub> V <sub>DC</sub>	20	30	40	45	50	60	80	100	150	200	V
RMS Reverse Voltage	V <sub>RMS</sub>	14	21	28	31	35	42	56	70	105	140	V
Average forward rectified output current @T <sub>A</sub> = 90°C	I <sub>O</sub>	2										A
Non-Repetitive Peak Forward Surge Current 8.3ms Single half sine-wave superimposed on rated load (JEDEC Method)	I <sub>FSM</sub>	50										A
Forward Voltage (per element) @I <sub>F</sub> = 2.0A	V <sub>FM</sub>	0.55			0.7		0.85		0.92			V
Peak Reverse Current @T <sub>A</sub> = 25°C At Rated DC Blocking Voltage @T <sub>A</sub> = 100°C	I <sub>RM</sub>	0.1 10					0.05 5					mA
Typical Junction Capacitance(per leg) (Note 1)	C <sub>J</sub>	28										pF
Typical Thermal Resistance (per leg) (Note 2)	R <sub>θJL</sub>	88										°C/W
Operating and Storage Temperature Range	T <sub>J</sub> , T <sub>STG</sub>	-55 to +150										°C

Note: 1. V<sub>R</sub> = 5V, T<sub>C</sub> = 25 °C, f<sub>SIG</sub> = 1MHz  
2. mounted on P.C. Board with 5.0mm<sup>2</sup> copper pad areas.

**Ratings and Characteristics Curves**

Fig. 1 Forward Current Derating Curve

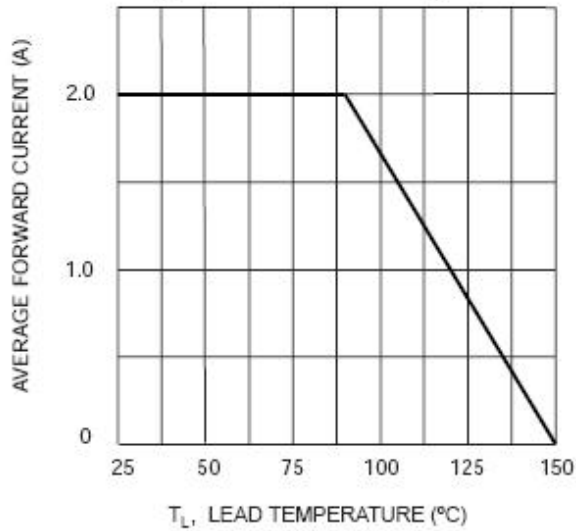


Fig. 2 Typ. Forward Characteristics

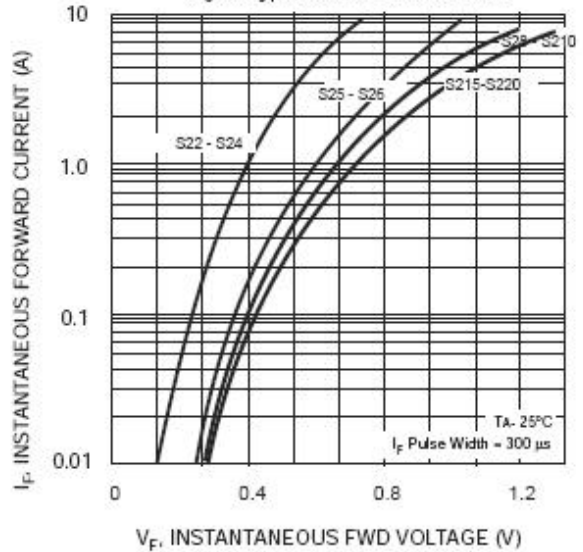


Fig. 3 Max Non-Repetitive Peak Fwd Surge Current

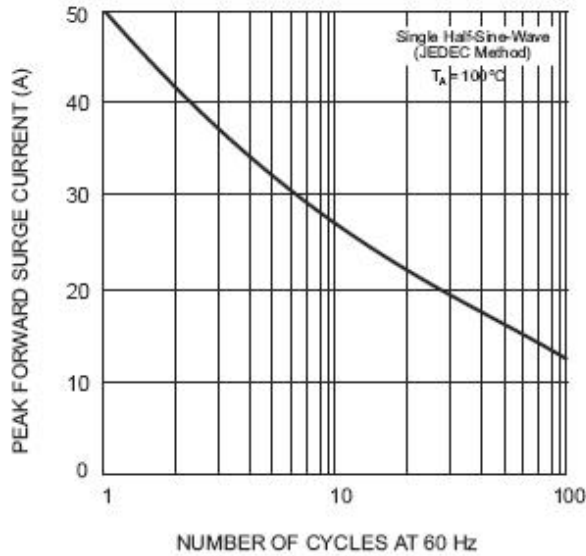
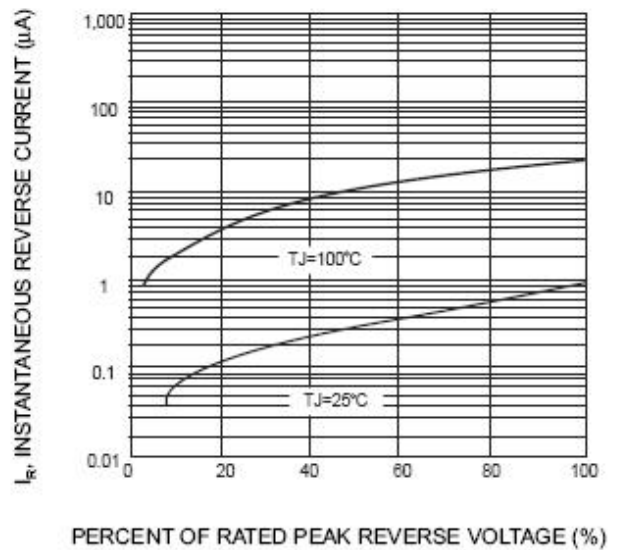
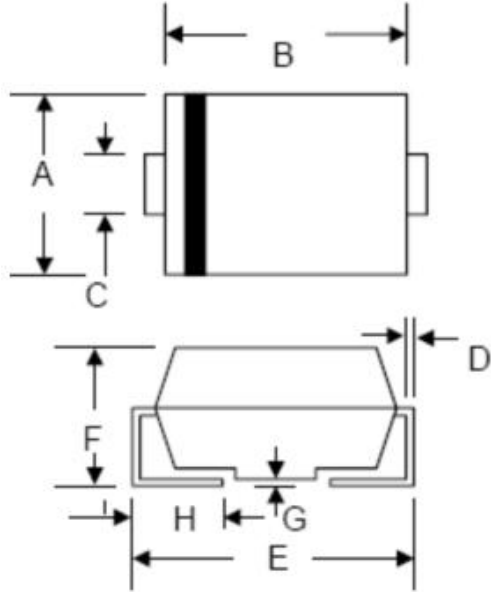


Fig. 4 Typical Reverse Characteristics (per element)



**Mechanical Dimensions SMA**



SYMBOL	Millimeters		Inches	
	Min.	Max.	Min.	Max.
A	2.40	2.84	0.094	0.112
B	3.99	4.75	0.157	0.187
C	1.05	1.70	0.041	0.067
D	0.15	0.51	0.006	0.020
E	4.80	5.66	0.189	0.223
F	1.90	2.95	0.075	0.116
G	0.05	0.25	0.002	0.010
H	0.76	1.52	0.030	0.600

**Ordering Information**

Device	Package	Shipping
SS22A - SS220A	SMA (Pb-Free)	5000pcs / reel

For information on tape and reel specifications, including part orientation and tape sizes, please refer to our tape and reel packaging specification.

**Marking Diagram**

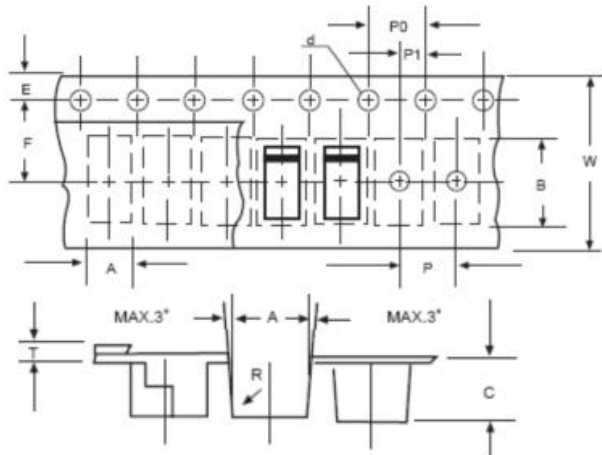


Where XXXXX is YYWWL

SS22A = Part Name  
YY = Year  
WW = Week  
L = Lot Number

**Cautions:** Molding resin  
Epoxy resin UL:94V-0

**Carrier Tape Specification SMA**



SYMBOL	Millimeters	
	Min.	Max.
A	2.97	3.17
B	5.70	5.90
C	2.32	2.52
d	1.40	1.60
E	1.40	1.60
F	5.60	5.70
P	3.90	4.10
P0	3.90	4.10
P1	1.90	2.10
T	0.25	0.35
W	11.80	12.20



SS22A  
THRU  
SS220A

**Technical Data**  
**Data Sheet N1816, Rev. A**



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